

**IN THE CLAIMS:**

Please cancel claim 5.

Please amend claims 1-4, 6-11, 15, and 16 as follows:

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1. (Once Amended) [-] An [un-packaged or semi-packaged,] electrically tested electronic device, free from infantile mortality, [characterized in that it] for direct mounting on a printed circuit board, wherein said electronic device comprises a silicon [platelet or] die [(11)] having a top surface and a bottom surface, in which an integrated circuit is realized externally accessible through a plurality of connection pads and an array of connection pins [(10; 13; 14)] which are mechanically and removably connected to said silicon die [(11)] by connection means for removable attachment of said pins, and are electrically connected to the connection pads of said silicon die [(11)] by electric connection means [(12)], said electronic device being unpackaged or partially packaged in a resin, wherein each of said connection pins includes a pre-formed portion which is not encapsulated in said resin, in order to accommodate the thermal expansion difference between the silicon die and the printed circuit board on which said electronic device is mounted.

2. (Once Amended) [-] An electronic device according to claim 1, [characterized in that] wherein said connection pads are arranged at the edges of [one] a first side of the silicon die [(11)] and said connection pins are affixed to the edges of a

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second side of the silicon die, wherein the first and second sides are opposite to one another. [the opposite side of said die (11).]

3. (Once Amended) [-] An electronic device according to claim 1, [characterized in that] wherein said connection pads are arranged along a central line on a side of said silicon die [(11)] and said connection pins [(10; 13)] are attached to the edges of the same side of the die [(11)].

4. (Twice Amended) [-] An electronic device according to claim 2, [characterized in that] wherein said connection means for removable attachment of said pins [(10; 13)] to said silicon die is [(11) are] a double-sided adhesive tape or a glue.

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6. (Once Amended) [-] An electronic device according to claim 1, [characterized in that] wherein said array of connection pins are realized as metallized strips [(14)] on a board of plastic material [(15)] removably attached to said silicon die [(11)] by means of a double-side adhesive tape or glue.

7. (Once Amended) [-] An electronic device according to claim 1, [characterized in that] wherein said pins are obtained by cutting a continuous strip support [(16)] on which said silicon dies [(11)] are mounted.

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8. (Twice Amended) [-] An electronic device according to claim 6,  
[characterized in that] wherein said connection pins are distributed on all four side edges  
of the die.

9. (Once Amended) [-] An electronic device according to claim 8,  
[characterized in that] wherein said electric connection means between said connection  
pins [(10; 13; 14)] and the connection pads of said silicon die are made by welded  
[micrometric] bonding wires [(12)].

10. (Once Amended) [-] An electronic device according to claim 9,  
[characterized in that] , wherein said electronic device is partially packaged in a resin so  
as to comprise a semi-package that covers [the] a first surface of the die where said  
connection pads are arranged together with their connections to the pins made by said  
bonding wires [(12)], as well as all flanks of the die, leaving [the] an opposite, second  
surface of the die exposed.

11. (Once Amended) [-] An electronic device according to claim 9,  
[characterized in that it] wherein said electronic device includes a three or more point[,]  
conductive bar aimed at distributing [the] an electric ground potential or power supply  
to three or more points of the die.